

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC9303xxxxKR-G

Typical Mass: 25 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.492	Silicon	59700	7440-21-3
	-	Arsenic	3	7440-38-2
Leadframe	10.472	Copper	418900	7440-50-8
	0.258	Iron	10300	7439-89-6
	0.014	Zinc	600	7440-66-6
	0.008	Phosphorus	300	7723-14-0
	0.552	Silver	22100	7440-22-4
Die attach	0.030	Silver	1200	7440-22-4
	0.010	Epoxy	400	—
Bonding wire	0.070	Gold	2800	7440-57-5
Resin	10.251	Silica	410000	60676-86-0
	0.762	Epoxy Resin	30500	—
	0.703	Phenol Resin	28100	—
Plating	0.378	Tin	15100	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."